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*Claim 5.* (AMENDED) The method as claimed in claim 2, wherein the outer surface layer of the cooling roll is formed of a material having a heat conductivity equal to or less than  $80\text{Wm}^{-1}\text{K}^{-1}$  at or around room temperature.

*Claim 6.* (AMENDED) The method as claimed in claim 2, wherein the outer surface layer of a cooling roll is formed of a material having a coefficient of thermal expansion in a range of  $3.5 - 18(\times 10^{-6}\text{K}^{-1})$  at or around room temperature.

*Claim 7.* (AMENDED) The method as claimed in claim 2, wherein an average thickness of the outer surface layer of the cooling roll is  $0.5$  to  $50\mu\text{m}$ .

*Claim 8.* (AMENDED) The method as claimed in claim 2, wherein an outer surface layer of the cooling roll is manufactured without experiencing a machining process.

*Claim 9.* (AMENDED) The method as claimed in claim 1, wherein a surface roughness  $\text{Ra}$  of a portion of the circumferential surface where the gas expelling means is not provided is  $0.05 - 5\mu\text{m}$ .

*Claim 11.* (AMENDED) The method as claimed in claim 10, wherein an average width of the groove is  $0.5 - 90\mu\text{m}$ .

*P1*

Claim 12. (AMENDED) The method as claimed in claim 10, wherein an average depth of the groove is 0.5 - 20 $\mu$ m.

*C1*

Claim 13. (AMENDED) The method as claimed in claim 10, wherein an angle defined by a longitudinal direction of the groove and a rotational direction of the cooling roll is equal to or less than 30 degrees.

*H2*

Claim 14. (AMENDED) The method as claimed in claim 10, wherein the groove is formed spirally with respect to a rotation axis of the cooling roll.

*D*

Claim 16. (AMENDED) The method as claimed in claim 10, wherein the groove has openings located at peripheral edges of the circumferential surface.

*S3*

Claim 17. (AMENDED) The method as claimed in claim 10, wherein a ratio of a projected area of the groove or grooves with respect to a projected area of the circumferential surface is 10 - 99.5%.

*A*

Claim 19. (AMENDED) A ribbon-shaped magnetic material which is manufactured by the method described in claim 1.

*R*

Claim 20. (AMENDED) The ribbon-shaped magnetic material as claimed in claim 19, wherein an average thickness thereof is 8 - 50 $\mu$ m.

*PS*

Claim 22. (AMENDED) The powdered magnetic material as claimed in claim 21, wherein the powdered magnetic material is subjected to at least one heat treatment during or after a manufacturing process thereof.

Claim 23. (AMENDED) The powdered magnetic material as claimed in claim 21, wherein a mean particle size of the powder is 1 - 300 $\mu\text{m}$ .

Claim 25. (AMENDED) The powdered magnetic material as claimed in claim 24, wherein a volume ratio of the  $\text{R}_2\text{TM}_{14}\text{B}$  phase with respect to the whole structural composition of the powdered magnetic material is equal to or greater than 80%.

Claim 26. (AMENDED) The powdered magnetic material as claimed in claim 24, wherein an average grain size of the  $\text{R}_2\text{TM}_{14}\text{B}$  type phase is equal to or less than 500nm.

Claim 27. A bonded magnet which is manufactured by binding the powdered magnetic material as claimed in claim 22 with a binding resin.

Claim 28. The bonded magnet as claimed in claim 27, wherein an intrinsic coercive force ( $H_{\text{cJ}}$ ) of the bonded magnet at room temperature lies within a range of 320 - 1200 kA/m.

*Cont*

*#6*  
Claim 29. The bonded magnet as claimed in claim 27, wherein a maximum magnetic energy product  $(BH)_{max}$  of the bonded magnet is equal to or greater than  $40\text{kJ/m}^3$ .

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